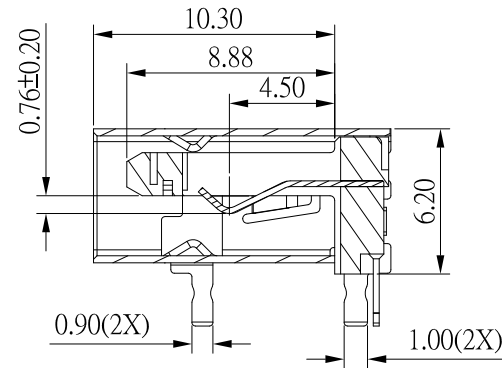
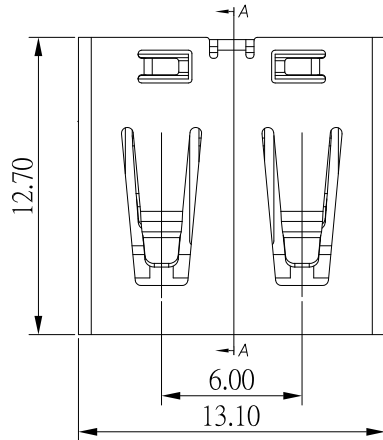
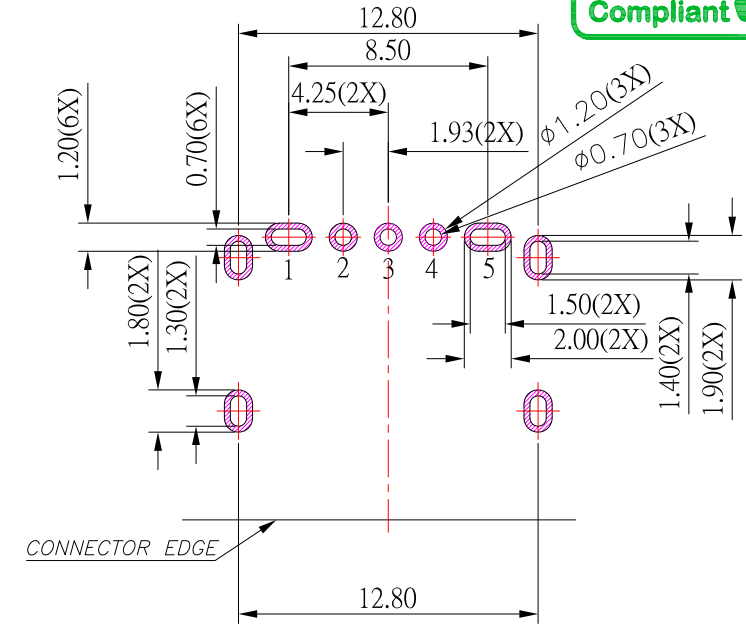
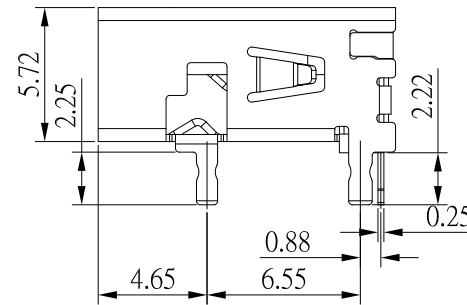
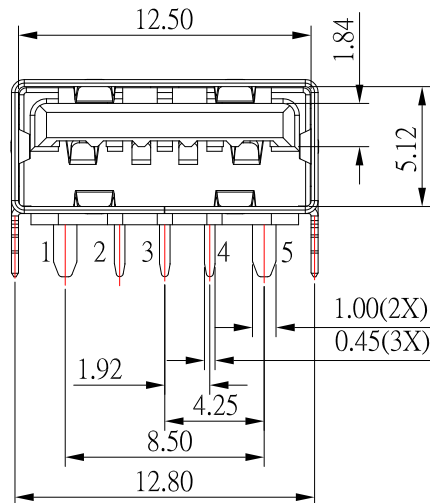


SUA-110H46-xx-S277

鍍層厚度 : _____ Color :

Blank : 1u"
2 : 15u"
3 : 30u"Black : B
Green : GR

SECTION:A-A



RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: PA10T
- 1.2 Contact: Copper Alloy
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 5.0 A(VBUS & GND)
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -25°C ~ +85°C
- 3.6 Insertion Force: 3.57 kgf Max
- 3.7 Extraction Force: 1.02 kgf Min

CONTACT建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.TOLERANCE UNLESS
OTHERWISE STATED :Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°3RD.
ANGEL'S

UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	05/26/20	FINISH	MODLE	USB AF 2.0 90度 DIP 5PIN 直腳 無捲邊
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110H46-xx-S277
Jacky Chen	05/26/20	1 : 1	PART NO.	SUA-110H46-xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	05/26/20			